

IN THE CLAIMS:

Please amend the claims as follows:

*Sub 52-1*  
52. (Previously Amended) A socket contact formation process, comprising:  
forming a contact head from a conductive material;  
forming a contact body from a semiconductive material configured to be electrically conductive;  
and  
joining said contact head and said contact body.

*53*  
53. (Original) The process in claim 52, wherein:  
said step of forming a contact head comprises stamping a metal element;  
said step of forming a contact body comprises etching silicon; and  
said step of joining said contact head and said contact body further comprises adhering said  
contact head onto said contact body.

54. (Original) The process in claim 52, wherein said step of joining said contact head  
and said contact body further comprises depositing a metal over a silicon surface.